

	<b>Typ e</b>	<b>Hits</b>	<b>Search Text</b>	<b>DBs</b>	<b>Time Stamp</b>	<b>Comment s</b>	<b>Error Definit ion</b>
1	BRS	8	(438/612.ccls. and polymer) and (conductive near polymer)	USPAT	2004/06/0 8 15:53		
2	BRS	48	438/612.ccls. and polymer	USPAT	2001/03/0 9 17:44		
3	BRS	2053	semiconductor near carrier	USPAT; EPO; JPO; DERWENT; IBM_TDB	2001/03/1 2 12:42		
4	BRS	0	(semiconductor near carrier) and membrane and (conductive near polymer)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2001/03/0 9 17:54		
5	BRS	22	(semiconductor near carrier) and membrane	USPAT; EPO; JPO; DERWENT; IBM_TDB	2001/03/0 9 17:48		

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6	BRS	5	((semiconductor near carrier) and membrane) and polymer) and conduct\$	USPAT; EPO; JPO; DERWENT; IBM_TDB	2001/03/09 17:48		Truncation Overflow. Return string from Server is: 5`0`0`C ON
7	BRS	6	(semiconductor near carrier) and (conductive near polymer)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2001/03/09 17:56		
8	BRS	0	(solder near bumps) and (conduct\$ near polymer)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2001/03/09 17:57		Truncation Overflow. Return string from Server is: 5`9`11` SO

	Typ e	Hits	Search Text	DBs	Time Stamp	Comments	Error Definit ion
9	BRS	2057	semiconductor near carrier	USPAT; EPO; JPO; DERWENT; IBM_TDB	2001/03/1 2 15:13		
10	BRS	6	(semiconductor near carrier) and membrane and polymer	USPAT; EPO; JPO; DERWENT; IBM_TDB	2001/03/1 2 12:43		
11	BRS	1065	438/118,119,613,614,65 0.ccls.	USPAT	2001/03/1 2 16:25		
12	BRS	32	438/118,119,613,614,65 0.ccls. and (conductive near polymer)	USPAT	2001/03/1 2 15:16		
13	BRS	211	(semiconductor near carrier) and gold	USPAT	2001/03/1 2 15:16		Truncat ion Overflo w. Return string from Server is: 5`0`0`C ON
14	BRS	3	((semiconductor near carrier) and gold) and (conduct\$ adj polymer)	USPAT	2001/03/1 2 15:11		

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15	BRS	4539	semiconductor near (carrier or carrier or assembly)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2001/03/1 2 15:14		
16	BRS	601	(semiconductor near (carrier or carrier or assembly)) and gold	USPAT	2001/03/1 2 15:16		
17	BRS	28	((semiconductor near (carrier or carrier or assembly)) and gold) and (conductive near polymer)	USPAT	2001/03/1 2 16:01		
18	BRS	441	epoxy near5 (bump or ball)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2001/03/1 2 16:02		
19	BRS	20	(epoxy near5 (bump or ball)) and (conductive near polymer)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2001/03/1 2 16:03		
20	BRS	1220	257/737, 738, 778.ccls.	USPAT	2001/03/1 2 16:25		
21	BRS	31	257/737, 738, 778.ccls. and (epoxy near5 (bump or ball))	USPAT	2001/03/1 2 18:28		
22	BRS	570	228/180.22.ccls.	USPAT	2001/03/1 2 16:49		

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23	BRS	13	228/180.22.ccls. and (epoxy near5 (bump or ball))	USPAT	2001/03/1 2 16:50		
24	BRS	7	(semiconductor near (carrier or carrier or assembly)) and (gold near ball)	USPAT	2001/03/1 2 18:29		
25	BRS	6	((semiconductor near carrier) and membrane ) and polymer	USPAT; EPO; JPO; DERWENT; IBM_TDB	2001/03/1 3 11:18		
26	BRS	1825	bump same (carrier or interposer) same chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/06/1 3 17:57		
27	BRS	99	(bump same (carrier or interposer) same chip) same (alternative\$ or interchange\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/06/1 3 18:47		
28	IS& R	1	("4875617").PN.	USPAT	2001/06/1 3 18:47		
29	IS& R	1	("6376352").PN.	USPAT	2004/06/0 8 11:14		

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30	BRS	4723	compliant and epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 11:14		
31	BRS	412	compliant with epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 11:15		
32	BRS	207	(compliant with epoxy) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 11:15		
33	BRS	57	((compliant with epoxy) and semiconductor) and BGA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 11:26		
34	BRS	95	bump with epoxy with coat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 11:26		

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35	BRS	30	(bump with epoxy with coat\$3) and gold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 11:27		